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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wolfgang Hetzel et al.

Serial No.: Unknown

(Priority Application No. DE 103 50 239.4)

(International Application No. PCT/DE2004/002374)

Filed: Herewith

(Priority Date: October 27, 2003)

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Docket No.: I431.156.101/FIN546PCT/US

Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING
COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND
METHOD FOR PRODUCING THE SAME

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Preliminary Amendment amends the Utility Patent Application filed herewith and should be used to calculate filing fees due. Prior to examination of the above-identified patent application, please amend as follows: